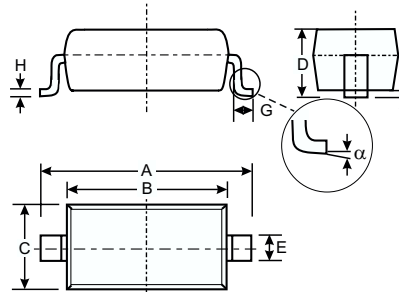


Features

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- High Surge Capability
- High Current Capability and Low Forward Voltage Drop

Mechanical Data

- Case: SOD-123, Plastic
- Plastic Material: UL Flammability Classification Rating 94V-0
- Moisture sensitivity: Level 1 per J-STD-020A
- Polarity: Cathode Band
- Terminals: Solderable per MIL-STD-202, Method 208
- Marking: Date Code & Type Code, See Page 3
- Type Code: SX
- Weight: 0.01 grams (approx.)
- Ordering Information: See Page 3



SOD-123		
Dim	Min	Max
A	3.55	3.85
B	2.55	2.85
C	1.40	1.70
D	—	1.35
E	0.55 Typical	
G	0.25	—
H	0.11 Typical	
J	—	0.10
α	0°	8°
All Dimensions in mm		

Maximum Ratings @ T_A = 25°C unless otherwise specified

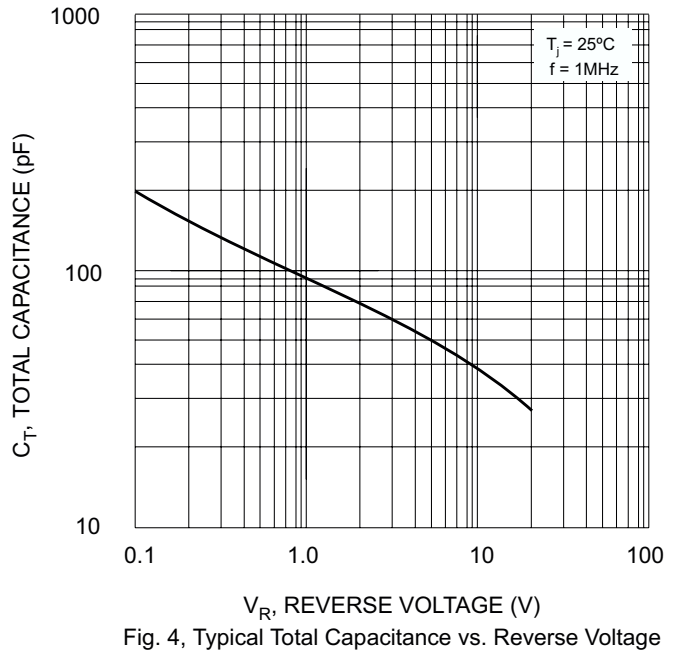
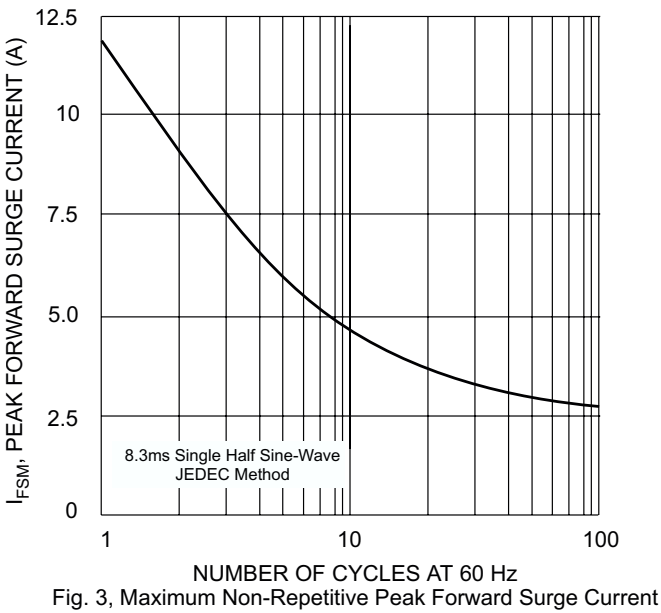
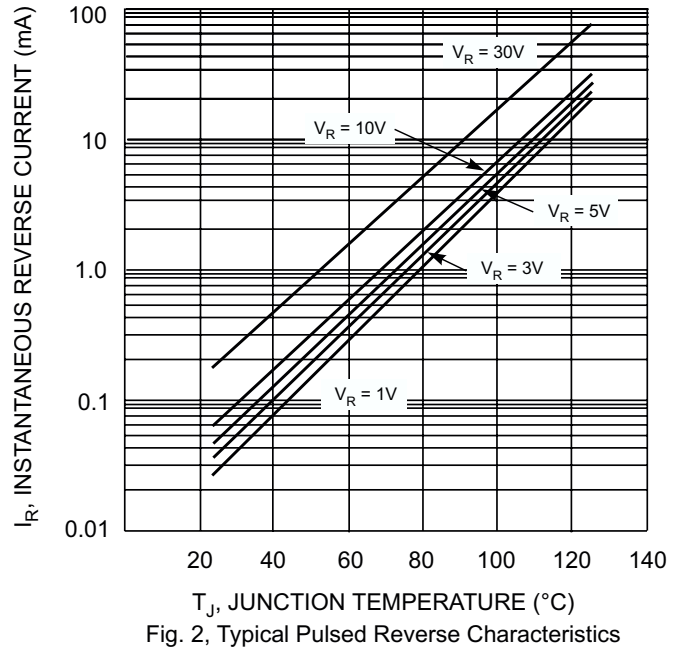
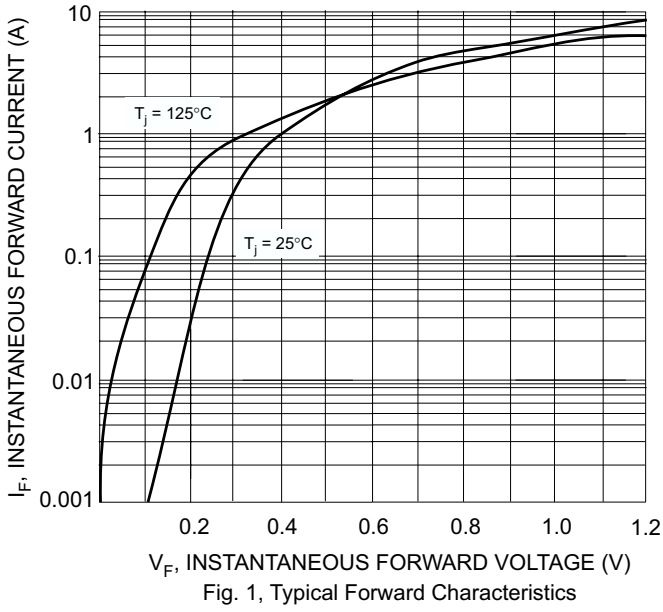
Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

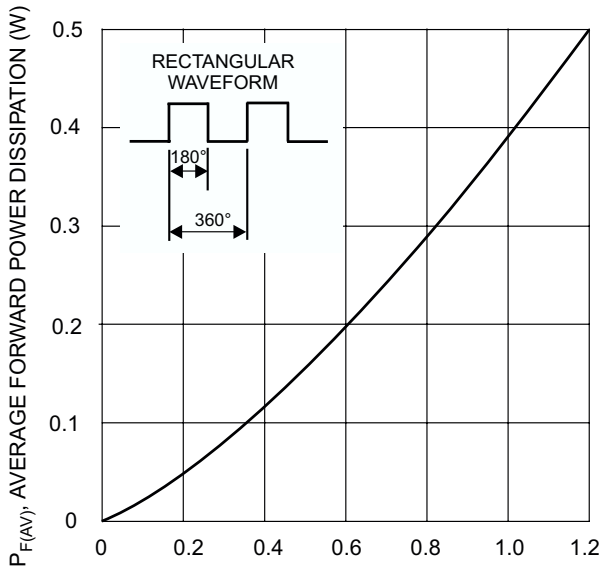
Characteristic	Symbol	B130LAW	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	21	V
Average Forward Current (See Figure 6)	I _{F(AV)}	1.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	12	A
Power Dissipation (Note 2)	P _d	450	mW
Typical Thermal Resistance Junction to Ambient (Note 2)	R _{θJA}	222	°C/W
Operating Temperature Range	T _j	-55 to +125	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C

Electrical Characteristics @ T_A = 25°C unless otherwise specified

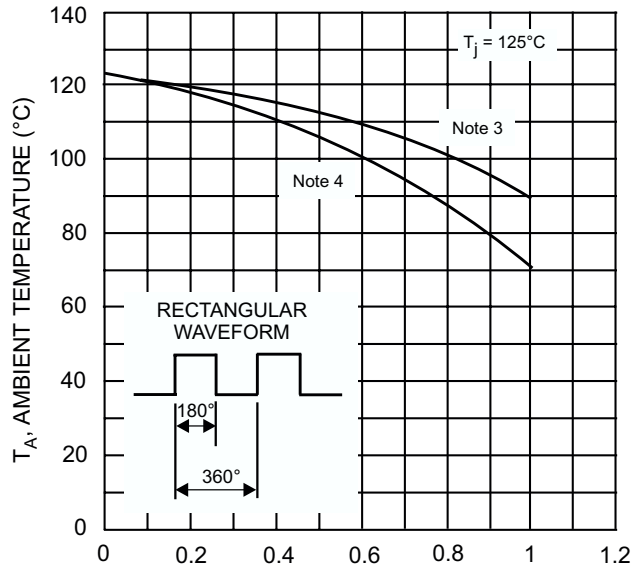
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 1)	V _{(BR)R}	30	—	—	V	I _R = 1.5mA
Forward Voltage (Note 1)	V _F	—	0.25 0.35 0.38	— 0.37 0.42	V	I _F = 0.1A I _F = 0.7A I _F = 1.0A
Leakage Current (Note 1)	I _R	—	0.15	1.0	mA	V _R = 30V, T _A = 25°C
Total Capacitance	C _T	—	40	—	pF	V _R = 10V, f = 1.0MHz

- Notes: 1. Short duration pulse test to minimize self-heating effect.
 2. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.





$I_{F(AVE)}$, AVERAGE FORWARD CURRENT (A)
Fig. 5, Forward Power Derating



$I_{F(AVE)}$, AVERAGE FORWARD CURRENT (A)
Fig. 6, Forward Current Derating

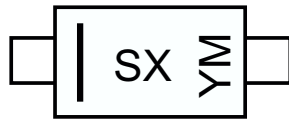
- Notes:
- 3. Device mounted on GETEK substrate, 2"x2", 2 oz. copper, double-sided, cathode pad dimensions 0.75" x 1.0", anode pad dimensions 0.25" x 1.0".
 - 4. Device mounted on FR-4 substrate, 2"x2", 2 oz. Copper, single-sided, pad layout as per Diodes Inc. suggested pad layout document AP02001 which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.

Ordering Information (Note 5)

Device	Packaging	Shipping
B130LAW-7	SOD-123	3000/Tape & Reel

- Notes:
- 5. For Packaging Details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



SX = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: N = 2002)
 M = Month (ex: 9 = September)

Date Code Key

Year	2002	2003	2004	2005	2006	2007	2008
Code	N	P	R	S	T	U	V

Month	Jan	Feb	March	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D